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(12) **United States Design Patent**
Okuma et al.

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(54) **LASER PROCESSING MACHINE**

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(73) Assignee: **HAMAMATSU PHOTONICS K.K.**, Hamamatsu (JP)

(**) Term: **15 Years**

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(22) Filed: **Apr. 29, 2019**

(30) **Foreign Application Priority Data**

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(51) **LOC (13) Cl.** **15-09**

(52) **U.S. Cl.**
USPC **D15/122**

(58) **Field of Classification Search**
USPC D15/122; D24/108, 164, 169, 170, 233; D16/230–234; D26/27; D10/81
(Continued)

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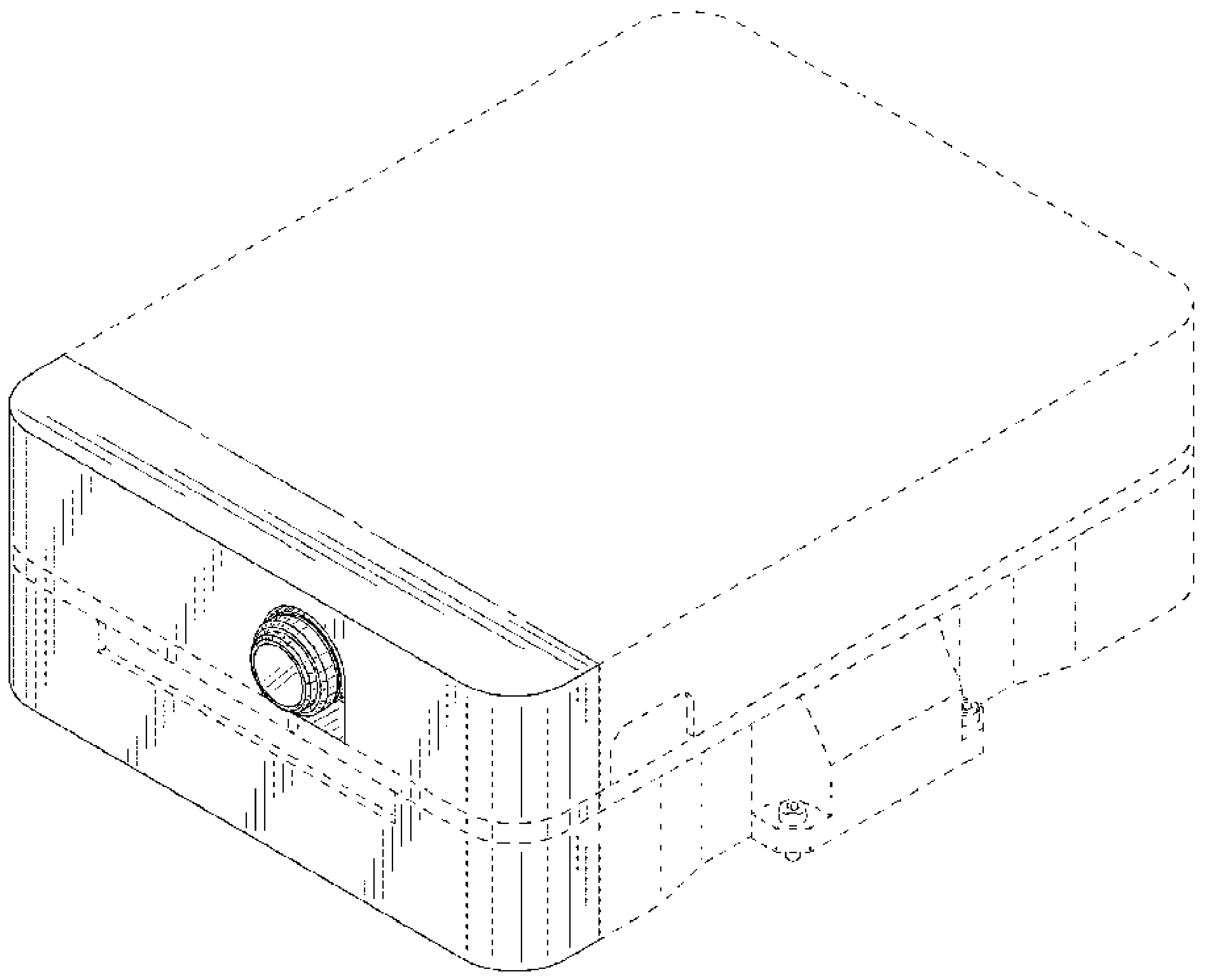
(57) **CLAIM**

The ornamental design for a laser processing machine, as shown and described.

DESCRIPTION

FIG. **1** is a front view of a laser processing machine of the present invention;
FIG. **2** is a rear view thereof;
FIG. **3** is a top plan view thereof;
FIG. **4** is a bottom plan view thereof;
FIG. **5** is a right side view thereof;
FIG. **6** is a left side view thereof;
FIG. **7** is a perspective view thereof;
FIG. **8** is an enlarged view thereof defined by the lines **8-8** and **8'-8'** in FIG. **1**;
FIG. **9** is an enlarged view thereof defined by the lines **9-9** and **9'-9'** in FIG. **1** showing the state of movement;
FIG. **10** is an enlarged view thereof defined by the lines **10-10** and **10'-10'** in FIG. **6**;
FIG. **11** is a sectional view thereof with inner mechanism is omitted taken along the line **11-11** in FIG. **10** of the portion defined by the line **11'-11'** in FIG. **3**; and,
FIG. **12** is an enlarged sectional view thereof with inner mechanism is omitted taken along the line **12-12** in FIG. **10** of the portion defined by the line **12'-12'** in FIG. **3**.
The broken lines showing of the laser processing machine is included for the purpose of illustrating portions of the article and forms no part of the claimed design.
The alternate long and short dash broken lines define the bounds of the claimed design and form no part thereof.

1 Claim, 12 Drawing Sheets



(58) **Field of Classification Search**

CPC B23K 26/00; B23K 26/0006; B23K 26/0096; B23K 26/08; B23K 26/36; B23K 26/32; B23K 26/40; F23G 2204/202; B01D 2259/808; B65C 2009/0043; B65C 2009/1846; B65H 2301/51536; B27K 5/005; B29C 2035/0838; H01L 21/00; H01L 21/67; H01L 2221/00; H01L 2221/67; H01L 22/10; H01L 23/32; H01L 23/544; H01S 3/00; H01S 3/0007; H01S 3/0014; H01S 3/025; H01S 3/101; H01S 5/00; H01S 5/02; H01S 5/04; H01S 5/10; H05K 3/0026

See application file for complete search history.

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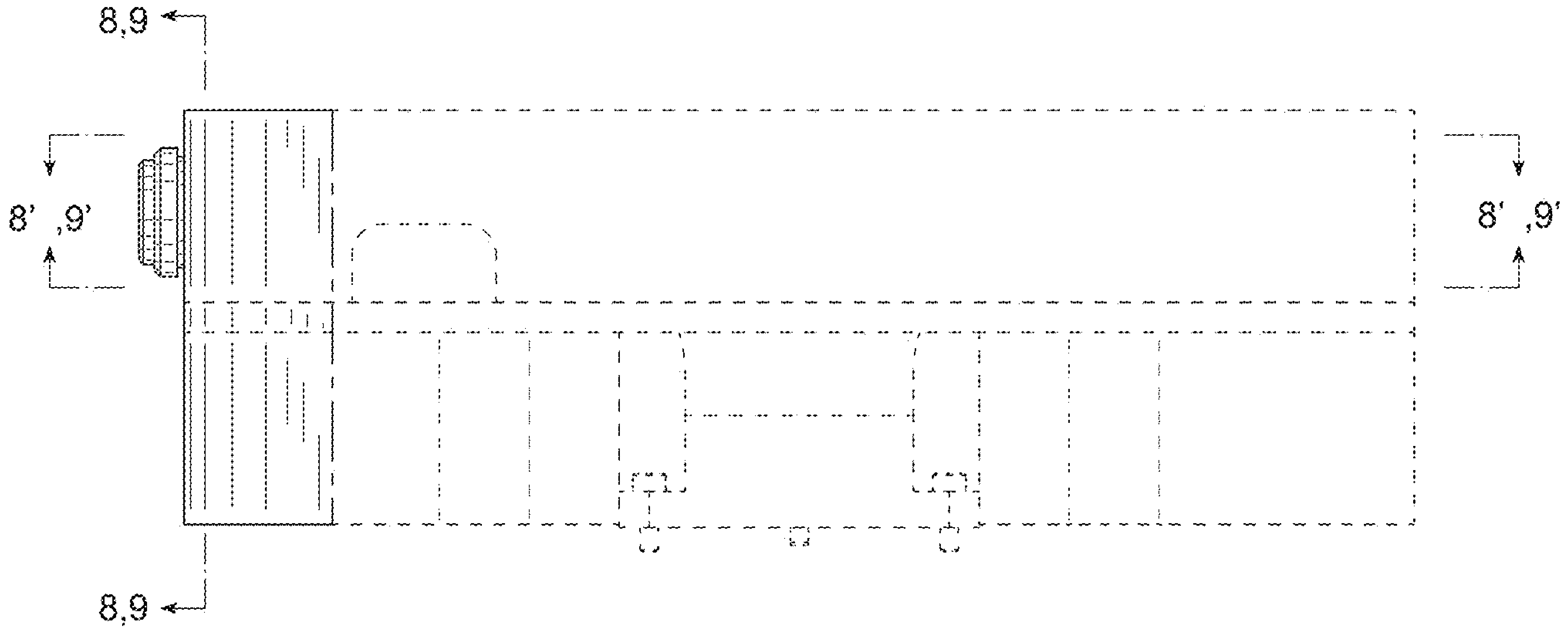

FIG. 1

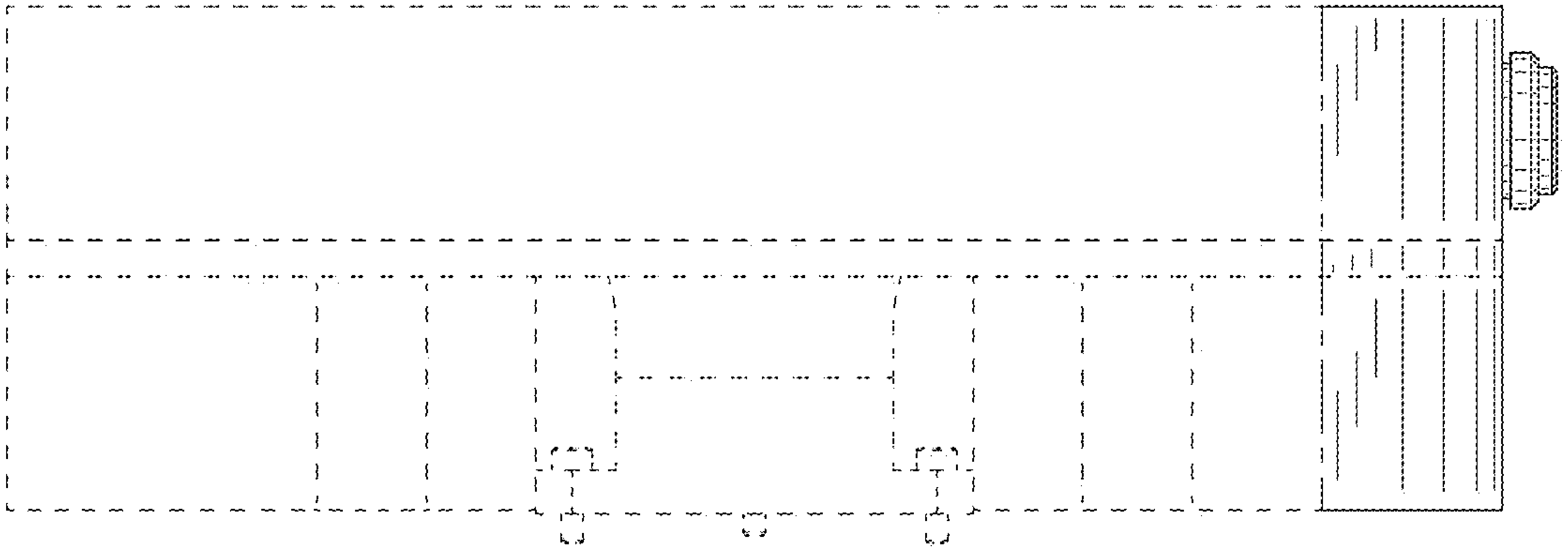

FIG. 2

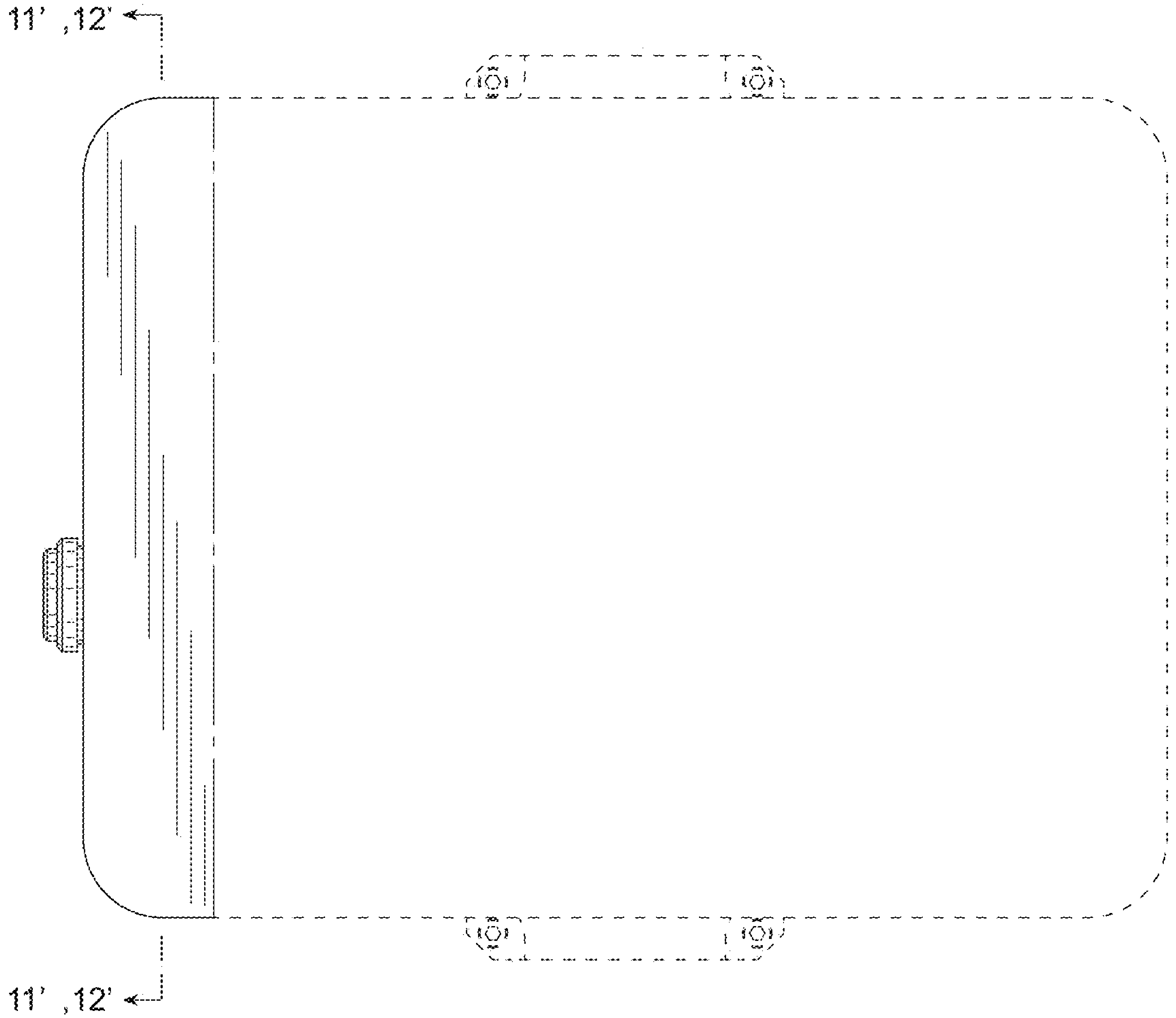

FIG. 3

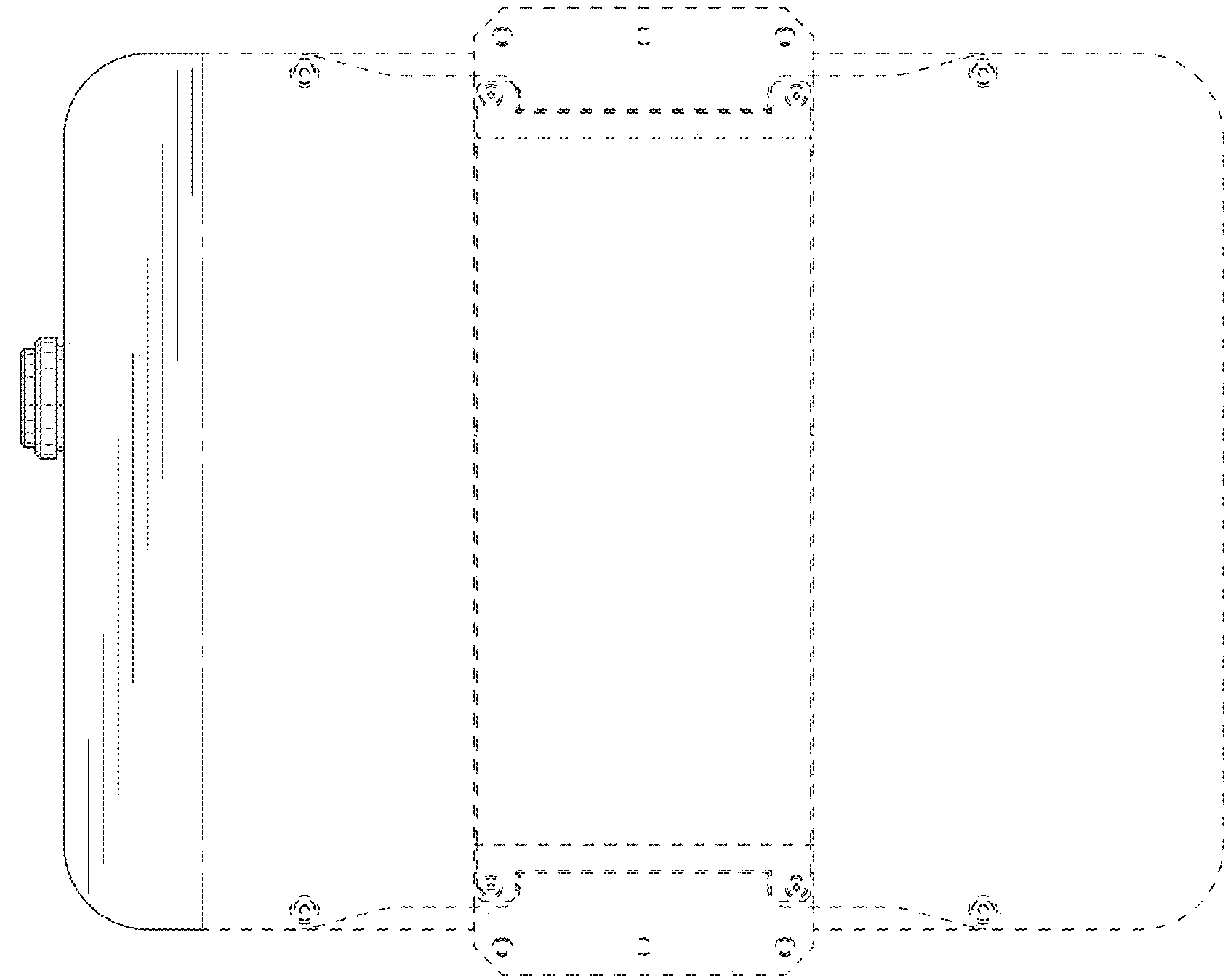

FIG. 4

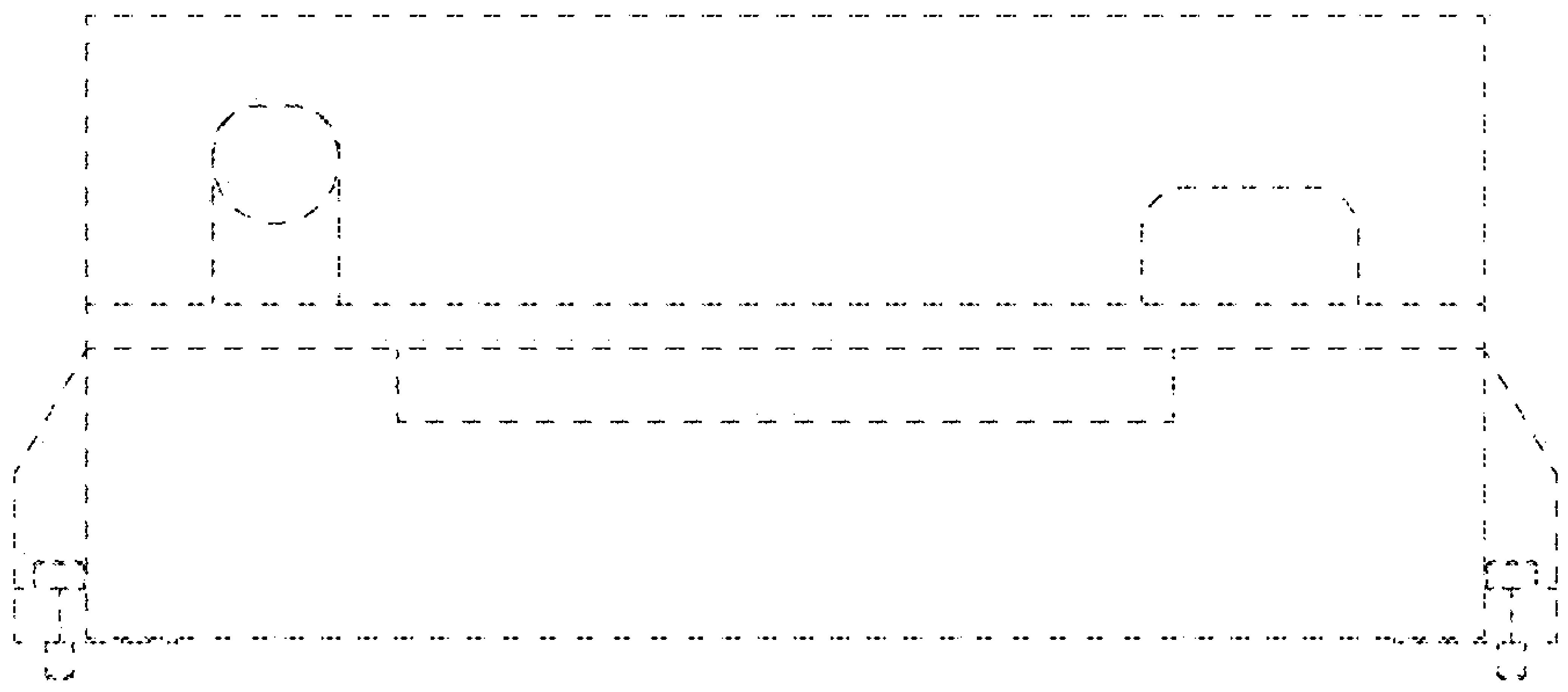

FIG. 5

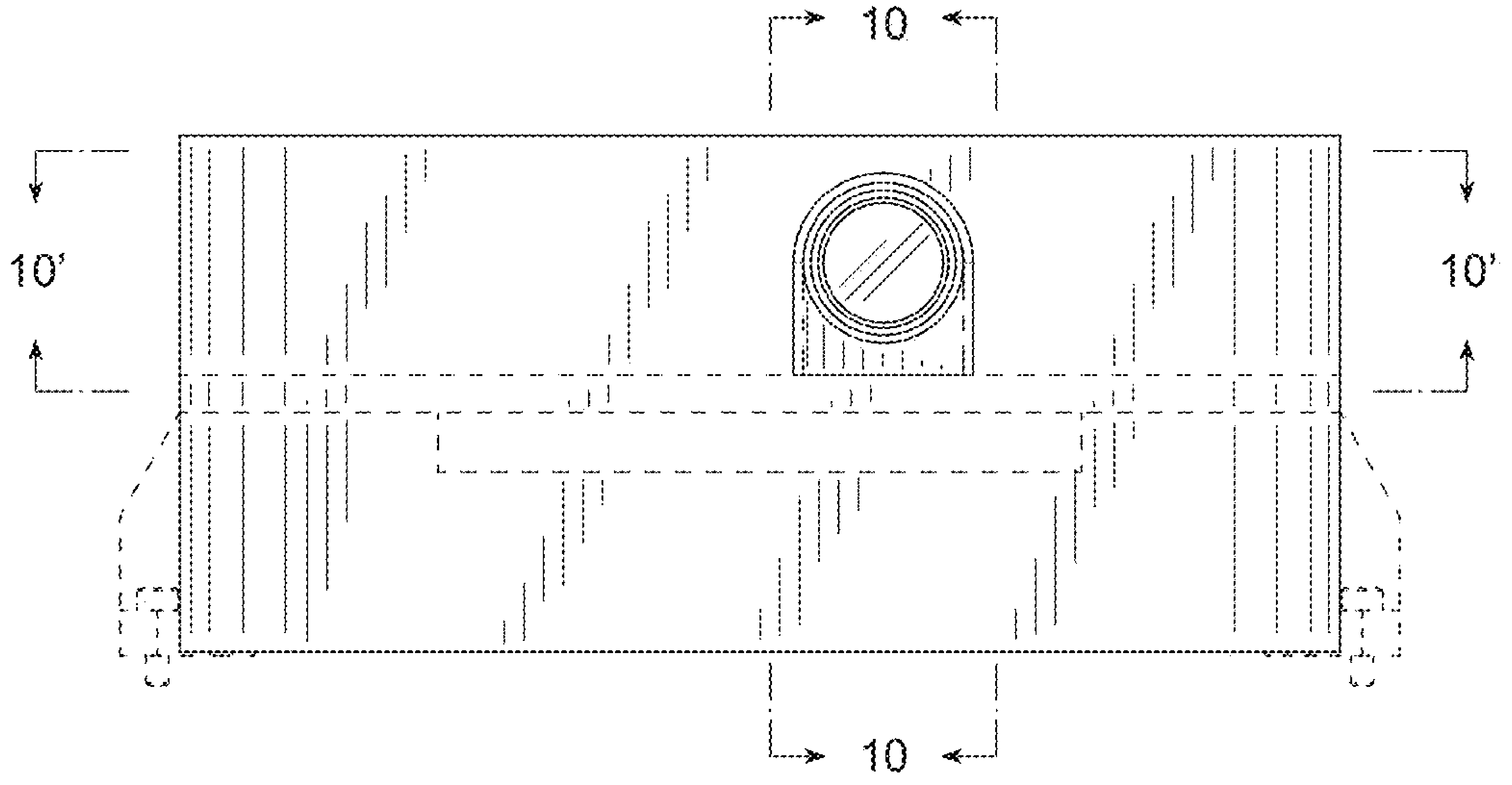

FIG. 6

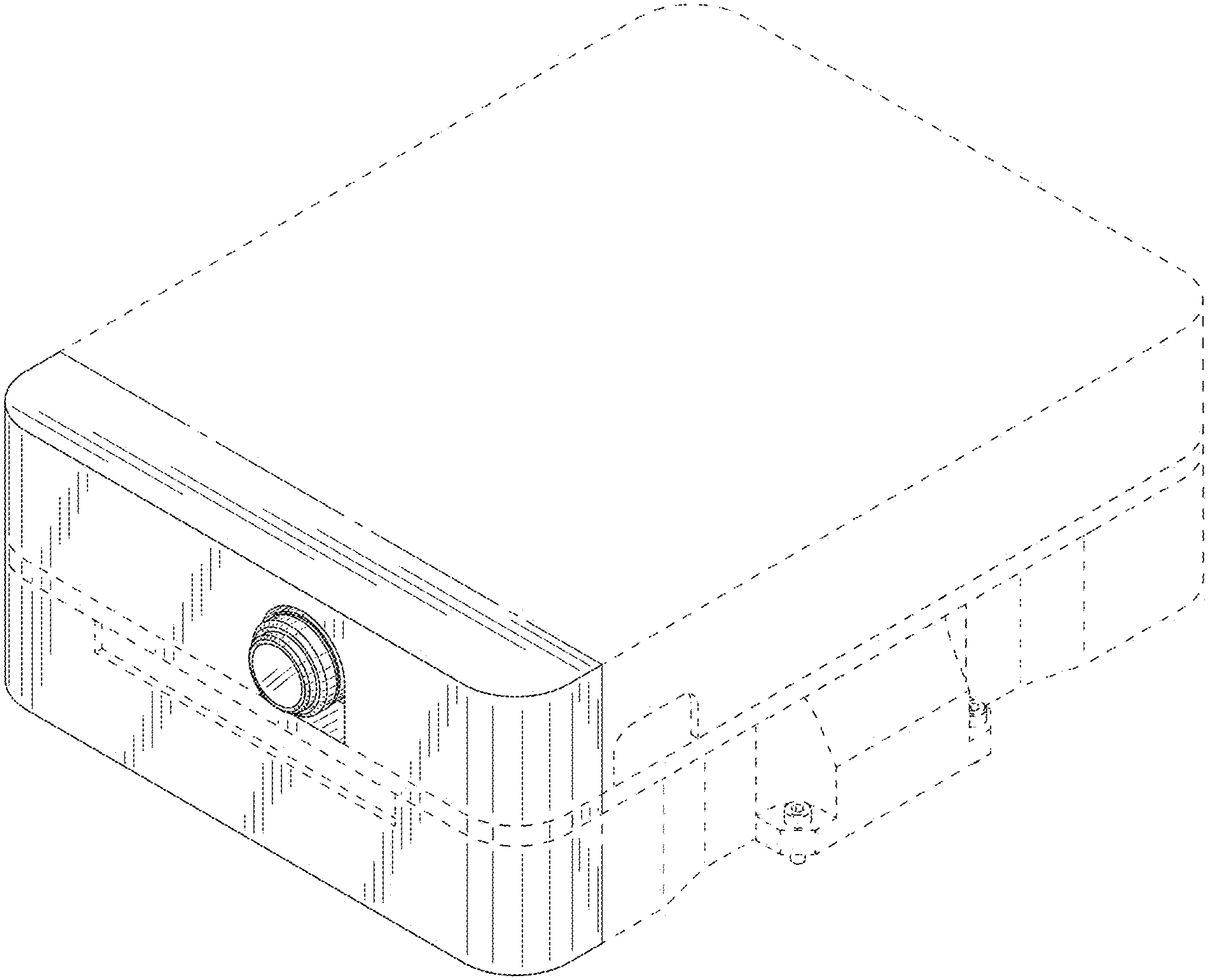

FIG. 7

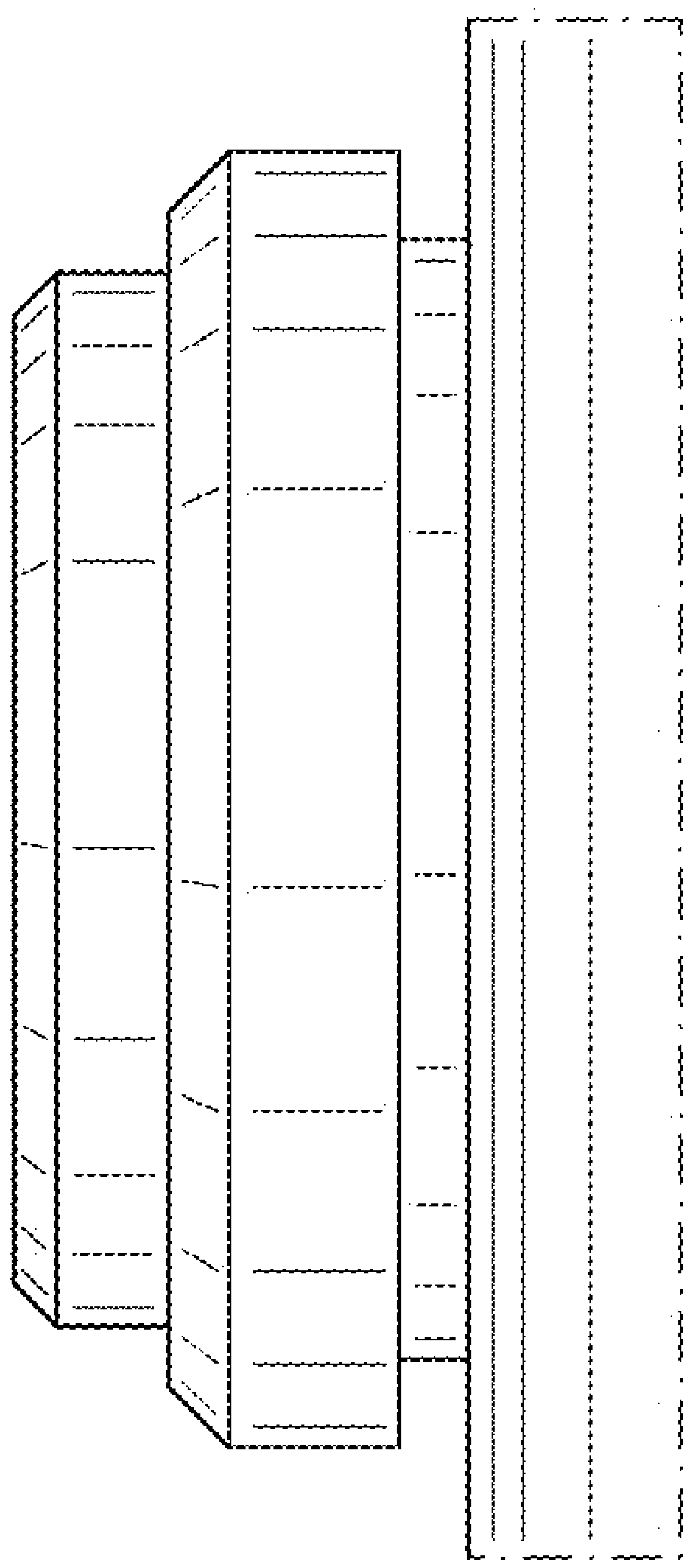

FIG. 8

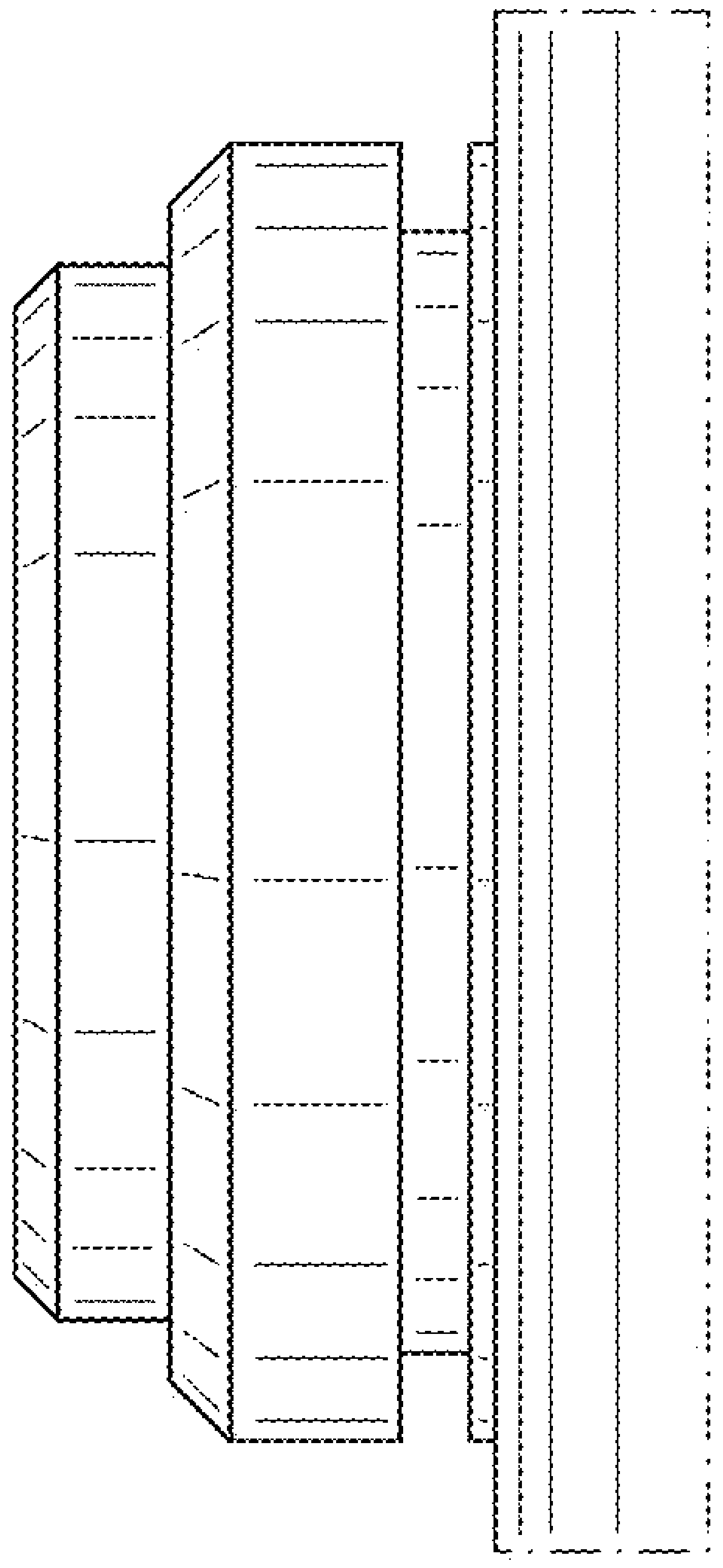

FIG. 9

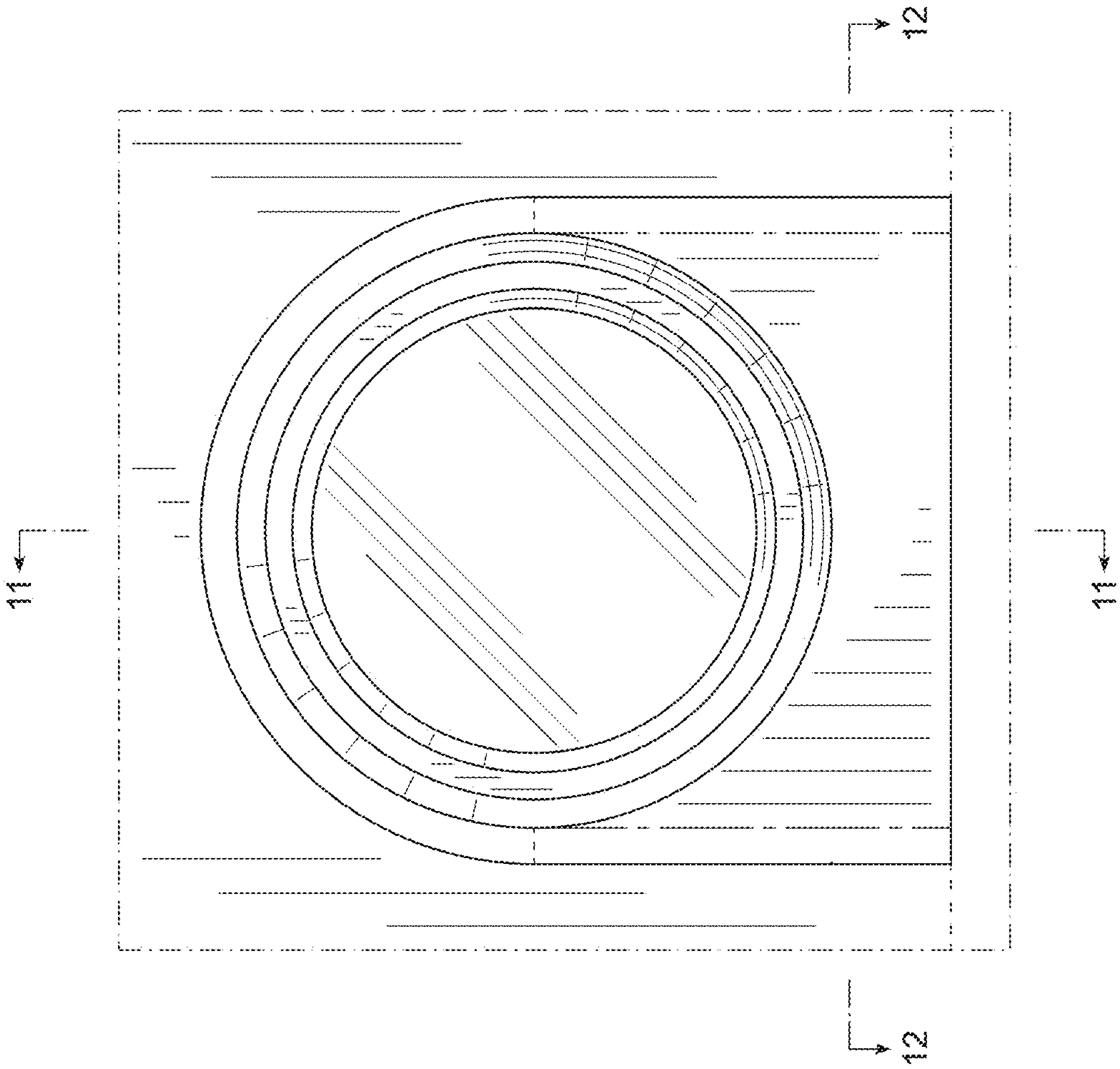

FIG. 10

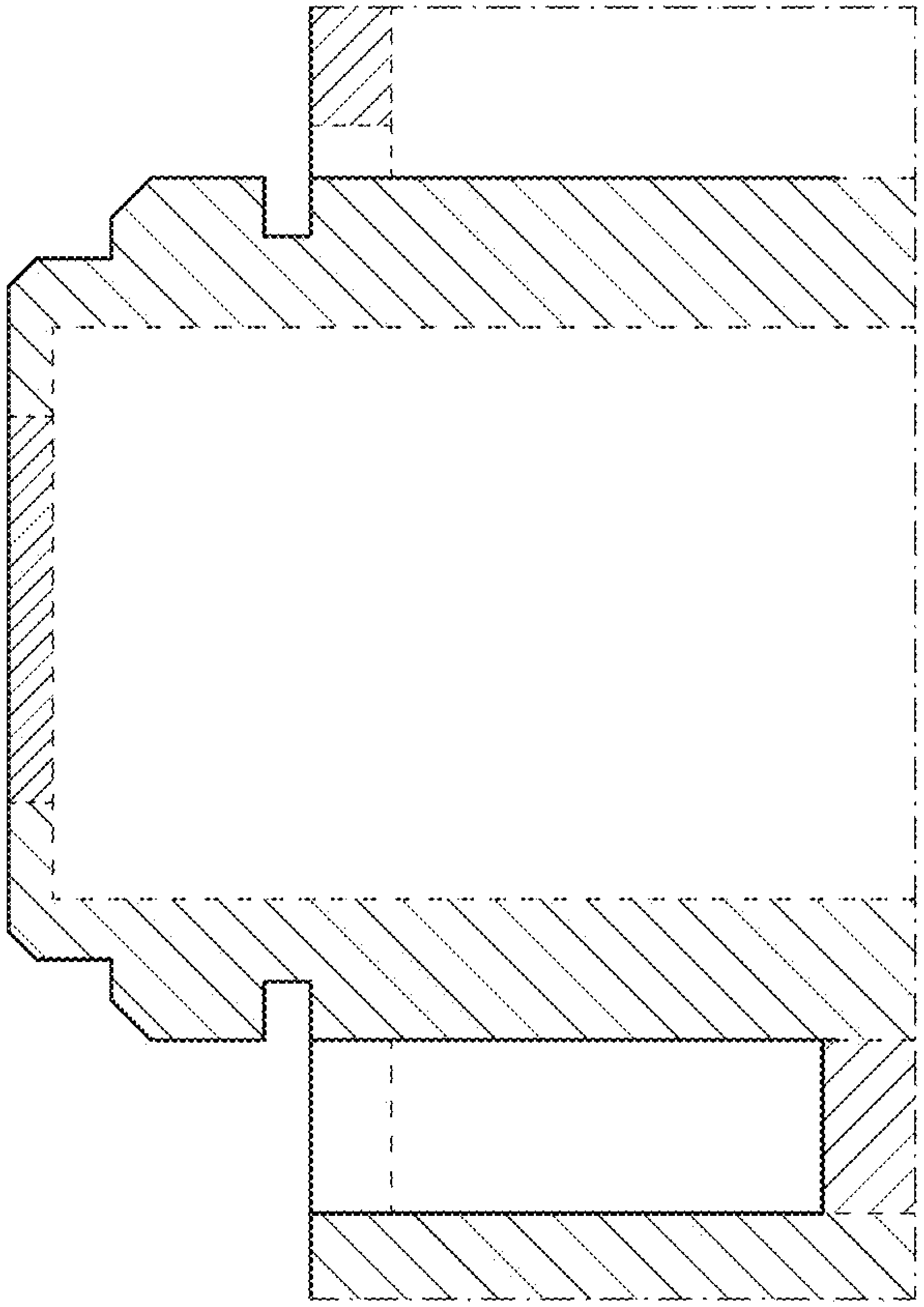

FIG. 11

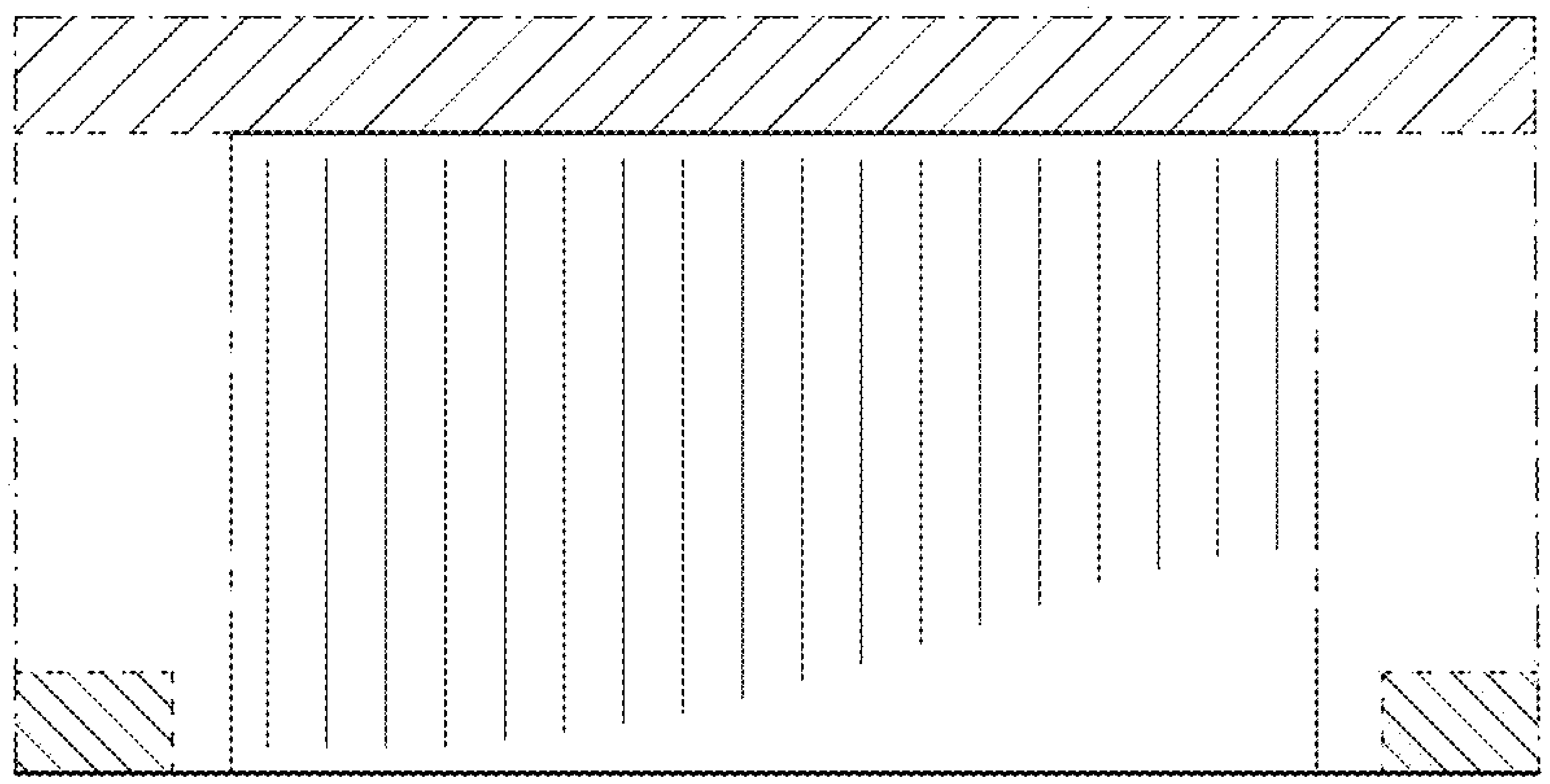

FIG. 12